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L Number	Hits	Search Text	DB	Time stamp
9	8	("4082394" "4322778" "5355283"	USPAT	2002/05/31
	°	"5537051" "5652185" "5777381"	OSPAI	07:59
1	_	"5977617" "5994773").PN.		
10	2	(("4082394" "4322778" "5355283"	USPAT	2002/05/31
		"5537051" "5652185" "5777381"		07:59
		"5977617" "5994773").PN.) and thermal		/
-	5939	semiconductor adj chip and resin	USPAT;	2002/05/29
			US-PGPUB	17:48
-	1754	(semiconductor adj chip and resin) and	USPAT;	2002/05/29
		encapsulat\$3	US-PGPUB	17:48
-	147	((semiconductor adj chip and resin) and	USPAT;	2002/05/30
		encapsulat\$3) and adhesive adj tape	US-PGPUB	18:53
-	60	((semiconductor adj chip and resin) and	USPAT;	2002/05/29
	.	encapsulat\$3) and pressure adj2 adhesive	US-PGPUB	17:58
-	34	("3908075" "4410905" "4539472"	USPAT	2002/05/29
		"4595945" "4598308" "4616413"		17:54
		"4754319" "4796078" "4862245"		
:		"4937203" "4965654" "4996587"		
		"5070390" "5075252" "5099309"		
1		"5140404" "5162264" "5170328"		
	1	"5177032" "5218229" "5220195"		
	1	"5227232" "5227338" "5227662" "5237201" "5250839" "5306670"		
1		, , , , , , , , , , , , , , , , , , , ,		
	1	"5349234" "5350947" "5382830" "5300003" "5412247" "5428247"		
İ	1	"5399903" "5412247" "5428247" "5481436").PN.		
	8	5696032.URPN.	USPAT	2002/05/29
-	ľ	J090032.URPN.	USPAI	17:56
1_	123	(((semiconductor adj chip and resin) and	USPAT;	2002/05/29
	123	encapsulat\$3) and adhesive adj tape) not	US-PGPUB	17:59
		(((semiconductor adj chip and resin) and	05-FGF0B	17.59
		encapsulat\$3) and pressure adj2 adhesive)		
<u>-</u>	1211	((semiconductor adj chip and resin) and	USPAT;	2002/05/29
	1211	encapsulat\$3) and (adhesive or tape)	US-PGPUB	18:00
l _	552	(((semiconductor adj chip and resin) and	USPAT;	2002/05/29
		encapsulat\$3) and (adhesive or tape)) and	US-PGPUB	17:59
		lead adj frame		
-	362	((((semiconductor adj chip and resin) and	USPAT;	2002/05/29
		encapsulat\$3) and (adhesive or tape)) and	US-PGPUB	18:03
		lead adj frame) and (tape)		
-	76	((((semiconductor adj chip and resin) and	USPAT;	2002/05/29
		encapsulat\$3) and adhesive adj tape) not	US-PGPUB	18:01
		(((semiconductor adj chip and resin) and		
		encapsulat\$3) and pressure adj2		
		adhesive)) and lead adj frame		
-	241	((((semiconductor adj chip and resin) and	USPAT;	2002/05/29
		encapsulat\$3) and (adhesive or tape)) and	US-PGPUB	18:03
		lead adj frame) and (tape) with lead		
-	40866	pressure adj sensitive	USPAT;	2002/05/29
],	US-PGPUB	18:04
-	1183	(pressure adj sensitive) and thermal adj	USPAT;	2002/05/29
	1 100	(shrinkage or expansion)	US-PGPUB	18:04
-	120	(pressure adj sensitive) same thermal adj	USPAT;	2002/05/29
1_		(shrinkage or expansion)	US-PGPUB	18:11
1 -	9	("3725115" "4379201" "4574879" "4714655" "4869879" "4908296"	USPAT	2002/05/29
	1	"4714655" "4869879" "4908296" "5213868" "5366573" "5462977").PN.		18:11
_	0	(("3725115" "4379201" "4574879"	HEDAT.	2002/05/20
	l "	(("3725115" "4379201" "4574879" "4714655" "4869879" "4908296"	USPAT;	2002/05/29
		"5213868" "5366573" "5462977").PN.)	US-PGPUB	18:19
1		same thermal adj (shrinkage or expansion)		
l _	0	(("3725115" "4379201" "4574879"	USPAT;	2002/05/29
	1	"4714655" "4869879" "4908296"	US-PGPUB	18:19
		"5213868" "5366573" "5462977").PN.)	JO EGEOD	10.15
		same thermal adj (contraction)		
-	0	(pressure adj sensitive) same thermal adj	USPAT;	2002/05/29
	l	(contraction)	US-PGPUB	18:19
-	25536	semiconductor adj chip	USPAT;	2002/05/30
			US-PGPUB	19:19

-	3186	(semiconductor adj chip) and thermal adj	USPAT;	2002/05/30
		(expansion or contraction or shrinkage)	US-PGPUB	19:19
-	292	(semiconductor adj chip) and thermal adj	USPAT;	2002/05/30
		(expansion or contraction or shrinkage)	US-PGPUB	19:06
		with (tape or adhesive)		
-	383	(semiconductor adj chip) and thermal adj	USPAT;	2002/05/30
		(expansion or contraction or shrinkage)	US-PGPUB	19:11
		with (tape or film)		1
-	220	(semiconductor adj chip) and thermal adj	USPAT;	2002/05/30
		(expansion or contraction or shrinkage)	US-PGPUB	19:08
		near5 (tape or film)		
-	220	((semiconductor adj chip) and thermal adj	USPAT;	2002/05/30
		(expansion or contraction or shrinkage)	US-PGPUB	19:14
		with (tape or film)) and thermal adj		1
		(expansion or contraction or shrinkage)		[
		near5 (tape or film)		
-	40	(((semiconductor adj chip) and thermal	USPAT;	2002/05/30
		adj (expansion or contraction or	US-PGPUB	19:17
		shrinkage) with (tape or film)) and		i
		thermal adj (expansion or contraction or		
		shrinkage) near5 (tape or film)) and "%"		
-	4	, , , ,	USPAT;	2002/05/30
		adj (expansion or contraction or	US-PGPUB	19:17
		shrinkage) with (tape or film)) and		
		thermal adj (expansion or contraction or		
		shrinkage) near5 (tape or film)) and "%"		
		with thermal		
-	42359	semiconductor adj chip	EPO; JPO;	2002/05/30
			DERWENT	19:19
-	1109	(semiconductor adj chip) and thermal adj	EPO; JPO;	2002/05/30
		(expansion or contraction or shrinkage)	DERWENT	19:19
-	167	(semiconductor adj chip) and thermal adj	EPO; JPO;	2002/05/30
		(expansion or contraction or shrinkage)	DERWENT	19:29
		with (tape or film or adhesive)		
-	1	("6284566").PN.	USPAT;	2002/05/30
			US-PGPUB	19:29
-	8	(USPAT	2002/05/31
		"5537051" "5652185" "5777381"	}	07:59
	<u> </u>	"5977617" "5994773").PN.	l	